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Product Change Notification

1. ECN #: 246867

2. Date of Announcement: April 21, 2015

3. Series:

- ERF8 - .8MM EDGE RATE SOCKET ASSEMBLY

4. Part #'s Affected

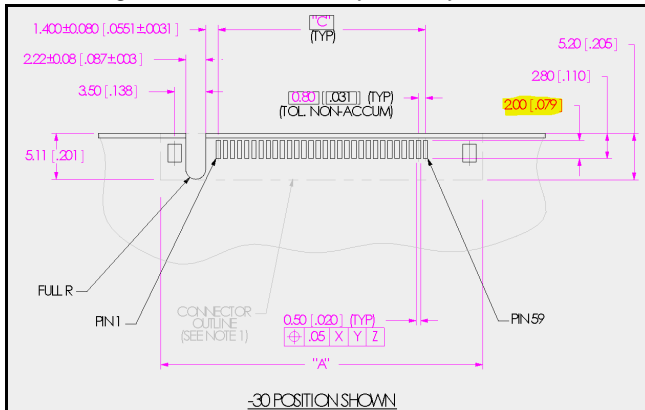
- ERF8-XXX-01-X-D-EMX-XXXX-TR

5. Description of Change:

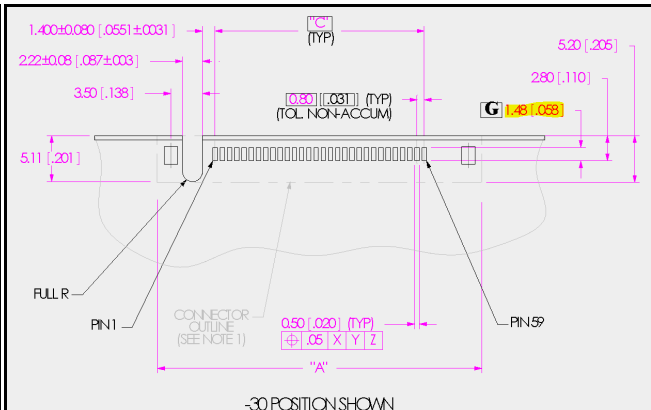
This change affects the PCB layout only. The recommended solder pad length is being reduced by 26% to reduce the risk of seeing a weaker solder joint. For the old revision, if the solder pad wets very well solder could migrate from the solder joint to cover the surface of the solder pad, which could lead to a less robust solder joint. On the new revision, if the solder pad wets very well the solder will have nowhere to migrate, forcing the solder to adhere to the lead, which will result in a very robust solder joint. The change is a design enhancement. Samtec has not seen any issues with the solder joints in the past, this revision is only an improvement to increase the possibilities of seeing an even stronger solder joint.

6. Method of Identifying Change

This change affects the PCB layout only.



ERF8-XXX-01-X-D-EMX-XXXX before the update.



ERF8-XXX-01-X-D-EMX-XXXX after the update.

7. Reason for Change:

The reason that this change is being communicated is to alert the customer of a design enhancement on the recommended PCB layout. Samtec does not deem the old revision problematic, but does recommend that any new boards ordered be manufactured to the latest footprint revision.

8. Impact of Change on Form, Fit, or Function:

- **Form** - The change is the reduction of the solder pad length on the recommended PCB layout. The reason for the change is to improve solder fillets and the overall strength of the solder joint.

9. Projected Implementation Date: May 13, 2015